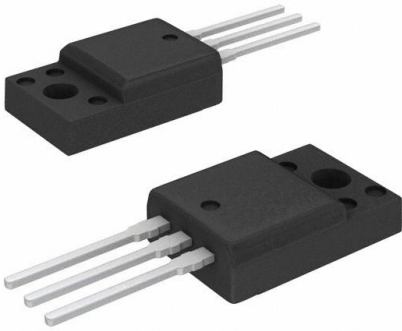


# FQPF10N60CT Datasheet

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|                              |  |
|------------------------------|--|
| DiGi Electronics Part Number | FQPF10N60CT-DG   |
| Manufacturer                 | <a href="#">onsemi</a>                                     |
| Manufacturer Product Number  | FQPF10N60CT  |
| Description                  | MOSFET N-CH 600V 9.5A TO220F                               |
| Detailed Description         | N-Channel 600 V 9.5A (Tc) 50W (Tc) Through Hole T O-220F-3 |



Tel: +00 852-30501935

RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

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## Purchase and inquiry

Manufacturer Product Number:

FQPF10N60CT

Series:

QFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

600 V

Drive Voltage (Max Rds On, Min Rds On):

10V

Vgs(th) (Max) @ Id:

4V @ 250µA

Vgs (Max):

±30V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

TO-220F-3

Base Product Number:

FQPF1

Manufacturer:

onsemi

Product Status:

Obsolete

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

9.5A (Tc)

Rds On (Max) @ Id, Vgs:

730mOhm @ 4.75A, 10V

Gate Charge (Qg) (Max) @ Vgs:

57 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

2040 pF @ 25 V

Power Dissipation (Max):

50W (Tc)

Mounting Type:

Through Hole

Package / Case:

TO-220-3 Full Pack

## Environmental & Export classification

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095





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November 2013

# FQP10N60C / FQPF10N60C

## N-Channel QFET® MOSFET

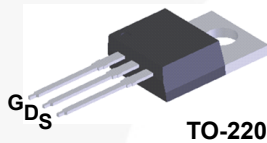
600 V, 9.5 A, 730 mΩ

### Description

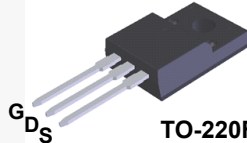
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to mini-mize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.

### Features

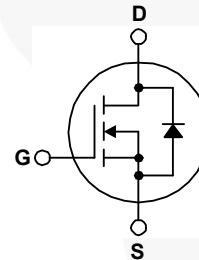
- 9.5 A, 600 V,  $R_{DS(on)} = 730 \text{ m}\Omega$  (Max.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 4.75 \text{ A}$
- Low Gate Charge (Typ. 44 nC)
- Low Crss (Typ. 18 pF)
- 100% Avalanche Tested



TO-220



TO-220F



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

| Symbol         | Parameter  | FQP10N60C   | FQPF10N60C | Unit                |
|----------------|--|-------------|------------|---------------------|
| $V_{DSS}$      | Drain-Source Voltage   | 600         |            | V                   |
| $I_D$          | Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )              | 9.5         | 9.5 *      | A                   |
|                | - Continuous ( $T_C = 100^\circ\text{C}$ )                           | 5.7         | 5.7 *      | A                   |
| $I_{DM}$       | Drain Current - Pulsed (Note 1)                                      | 38          | 38 *       | A                   |
| $V_{GSS}$      | Gate-Source Voltage  | $\pm 30$    |            | V                   |
| $E_{AS}$       | Single Pulsed Avalanche Energy (Note 2)                              | 700         |            | mJ                  |
| $I_{AR}$       | Avalanche Current (Note 1)   | 9.5         |            | A                   |
| $E_{AR}$       | Repetitive Avalanche Energy (Note 1)                                 | 15.6        |            | mJ                  |
| dv/dt          | Peak Diode Recovery dv/dt (Note 3)                                   | 4.5         |            | V/ns                |
| $P_D$          | Power Dissipation ( $T_C = 25^\circ\text{C}$ )                       | 156         | 50         | W                   |
|                | - Derate above $25^\circ\text{C}$                                    | 1.25        | 0.4        | W/ $^\circ\text{C}$ |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                              | -55 to +150 |            | $^\circ\text{C}$    |
| $T_L$          | Maximum lead temperature for soldering, 1/8" from case for 5 seconds | 300         |            | $^\circ\text{C}$    |

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

| Symbol          | Parameter                                     | FQP10N60C | FQPF10N60C | Unit                      |
|-----------------|---|-----------|------------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max.    | 0.8       | 2.5        | $^\circ\text{C}/\text{W}$ |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink, Typ.        | 0.5       | --         | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 62.5      | 62.5       | $^\circ\text{C}/\text{W}$ |

## Package Marking and Ordering Information

| Part Number     | Top Mark    | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-----------------|-------------|---------|----------------|-----------|------------|----------|
| FQP10N60C       | FQP10N60C   | TO-220  | Tube           | N/A       | N/A        | 50 units |
| FQPF10N60C      | FQPF10N60C  | TO-220F | Tube           | N/A       | N/A        | 50 units |
| FQPF10N60CT     | FQPF10N60CT | TO-220F | Tube           | N/A       | N/A        | 50 units |
| FQPF10N60C_F105 | FQPF10N60C  | TO-220F | Tube           | N/A       | N/A        | 50 units |

## Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted.

| Symbol  | Parameter   | Test Conditions   | Min      | Typ  | Max  | Unit |
|---|---|---|----------|------|------|------|
| <b>Off Characteristics</b>                                    |   |   |          |      |      |      |
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                        | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA                                    | 600      | --   | --   | V    |
| ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>                          | Breakdown Voltage Temperature Coefficient             | I <sub>D</sub> = 250 μA, Referenced to 25°C                                       | --       | 0.7  | --   | V/°C |
| I <sub>DSS</sub>  | Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V                                    | --       | --   | 1    | μA   |
|   |   | V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C                                   | --       | --   | 10   | μA   |
| I <sub>GSSF</sub>   | Gate-Body Leakage Current, Forward                    | V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V                                     | --       | --   | 100  | nA   |
| I <sub>GSSR</sub>   | Gate-Body Leakage Current, Reverse                    | V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V                                    | --       | --   | -100 | nA   |
| <b>On Characteristics</b>                                     |   |   |          |      |      |      |
| V <sub>GS(th)</sub>   | Gate Threshold Voltage                                | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                       | 2.0      | --   | 4.0  | V    |
| R <sub>DS(on)</sub>   | Static Drain-Source On-Resistance                     | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.75 A                                   | --       | 0.6  | 0.73 | Ω    |
| g <sub>FS</sub>   | Forward Transconductance                              | V <sub>DS</sub> = 40 V, I <sub>D</sub> = 4.75 A                                   | --       | 8.0  | --   | S    |
| <b>Dynamic Characteristics</b>                                |   |   |          |      |      |      |
| C <sub>iss</sub>  | Input Capacitance                                     | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,<br>f = 1.0 MHz                     | --       | 1570 | 2040 | pF   |
| C <sub>oss</sub>  | Output Capacitance                                    |   | --       | 166  | 215  | pF   |
| C <sub>rss</sub>  | Reverse Transfer Capacitance                          |   | --       | 18   | 24   | pF   |
| <b>Switching Characteristics</b>                              |   |   |          |      |      |      |
| t <sub>d(on)</sub>  | Turn-On Delay Time                                    | V <sub>DD</sub> = 300 V, I <sub>D</sub> = 9.5A,<br>R <sub>G</sub> = 25 Ω          | --       | 23   | 55   | ns   |
| t <sub>r</sub>  | Turn-On Rise Time                                     |   | --       | 69   | 150  | ns   |
| t <sub>d(off)</sub>   | Turn-Off Delay Time                                   |   | --       | 144  | 300  | ns   |
| t <sub>f</sub>  | Turn-Off Fall Time                                    |   | (Note 4) | --   | 77   | 165  |
| Q <sub>g</sub>  | Total Gate Charge                                     | V <sub>DS</sub> = 480 V, I <sub>D</sub> = 9.5A,<br>V <sub>GS</sub> = 10 V         | --       | 44   | 57   | nC   |
| Q <sub>gs</sub>   | Gate-Source Charge                                    |   | --       | 6.7  | --   | nC   |
| Q <sub>gd</sub>   | Gate-Drain Charge                                     |   | (Note 4) | --   | 18.5 | --   |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |   |   |          |      |      |      |
| I <sub>S</sub>  | Maximum Continuous Drain-Source Diode Forward Current |   | --       | --   | 9.5  | A    |
| I <sub>SM</sub>   | Maximum Pulsed Drain-Source Diode Forward Current     |   | --       | --   | 38   | A    |
| V <sub>SD</sub>   | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9.5 A                                     | --       | --   | 1.4  | V    |
| t <sub>rr</sub>   | Reverse Recovery Time                                 | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9.5 A,<br>dI <sub>F</sub> / dt = 100 A/μs | --       | 420  | --   | ns   |
| Q <sub>rr</sub>   | Reverse Recovery Charge                               |   | --       | 4.2  | --   | μC   |

### NOTES:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. L = 14.2 mH, I<sub>AS</sub> = 9.5 A, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25 Ω, starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub> ≤ 9.5 A, di/dt ≤ 200 A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, starting T<sub>J</sub> = 25°C.
4. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

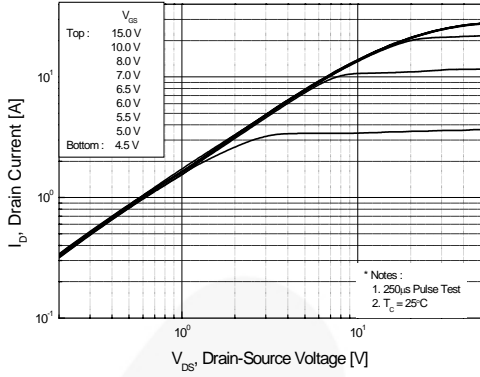


Figure 2. Transfer Characteristics

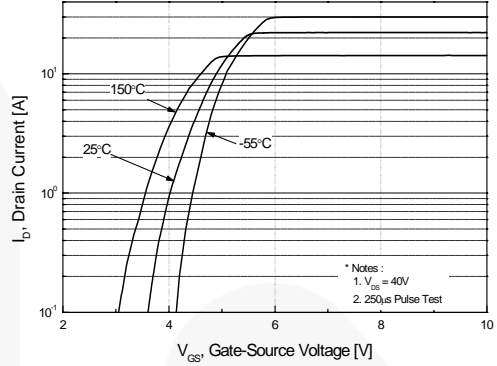


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

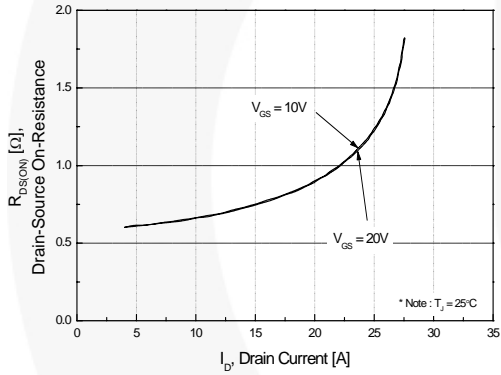


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

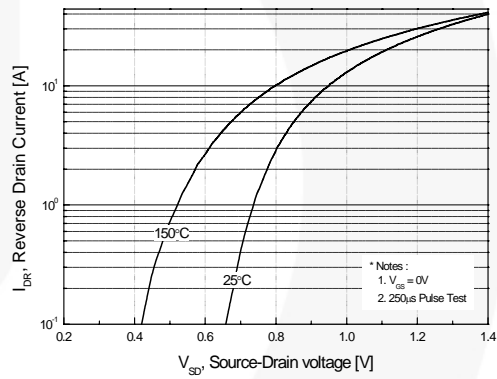


Figure 5. Capacitance Characteristics

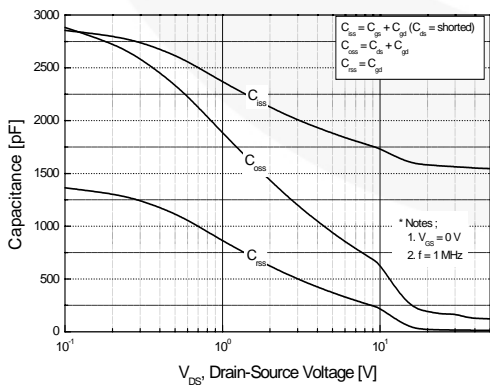
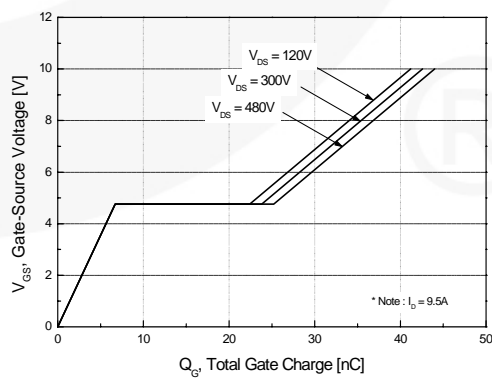
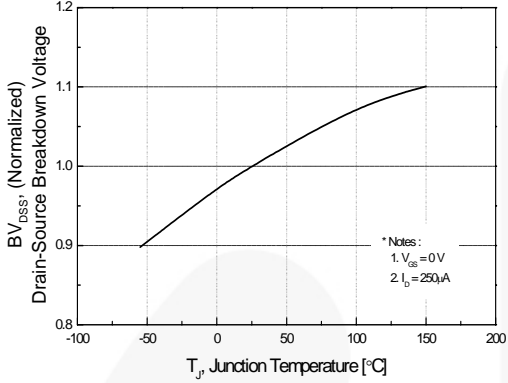


Figure 6. Gate Charge Characteristics

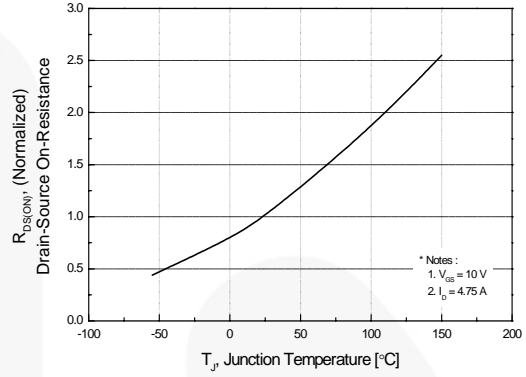


**Typical Performance Characteristics** (Continued)

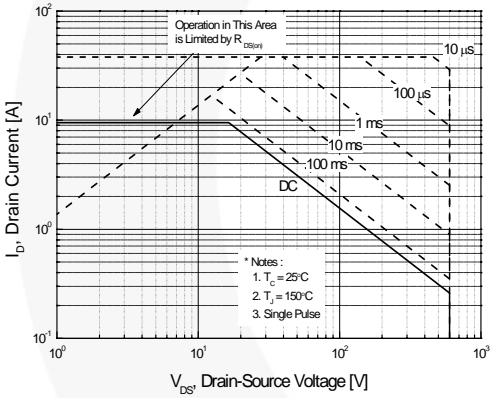
**Figure 7. Breakdown Voltage Variation vs. Temperature**



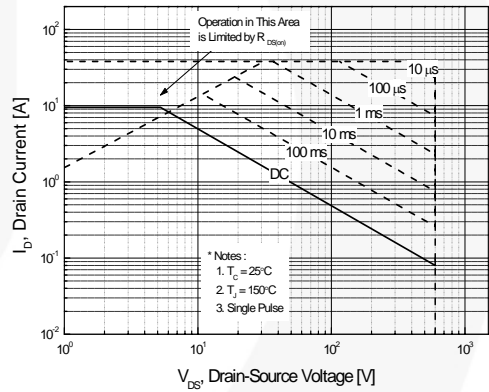
**Figure 8. On-Resistance Variation vs. Temperature**



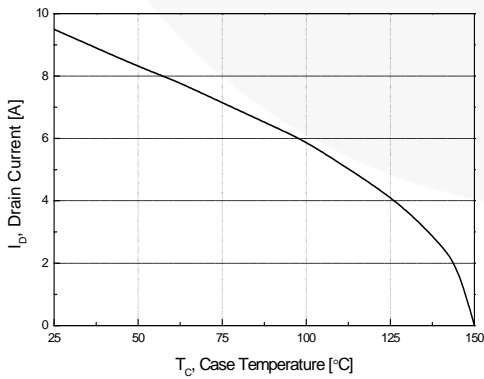
**Figure 9-1. Maximum Safe Operating Area for FQP10N60C**



**Figure 9-2. Maximum Safe Operating Area for FQPF10N60C**



**Figure 10. Maximum Drain Current vs. Case Temperature**



Typical Performance Characteristics (Continued)

Figure 11-1. Transient Thermal Response Curve for FQP10N60C

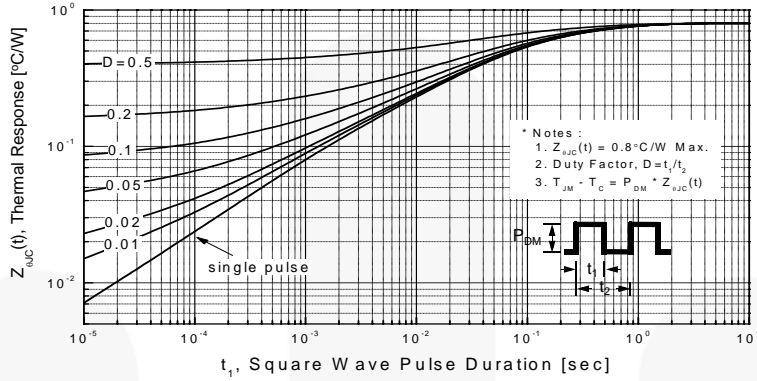
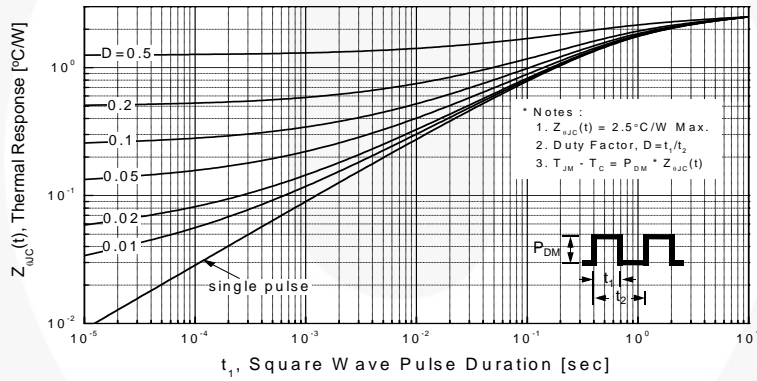


Figure 11-2. Transient Thermal Response Curve for FQPF10N60C





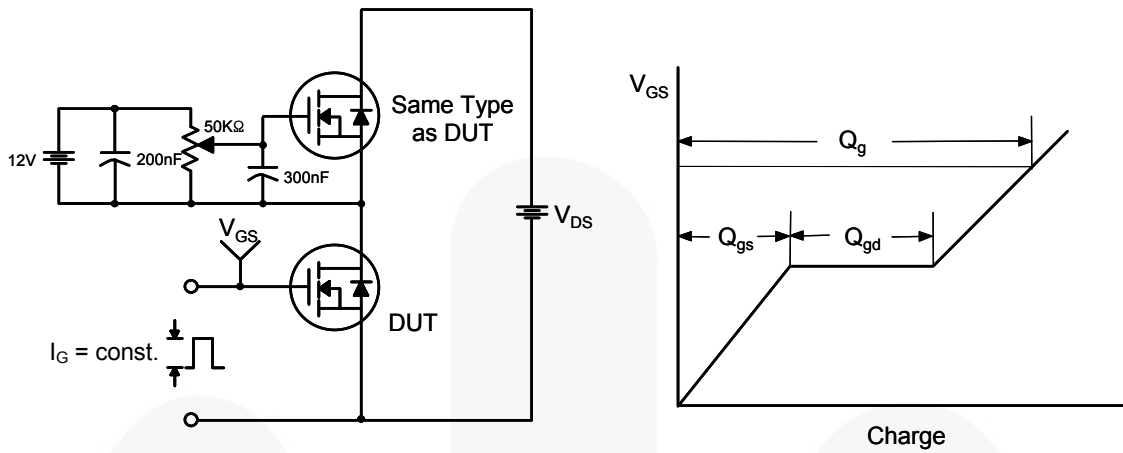


Figure 12. Gate Charge Test Circuit & Waveform

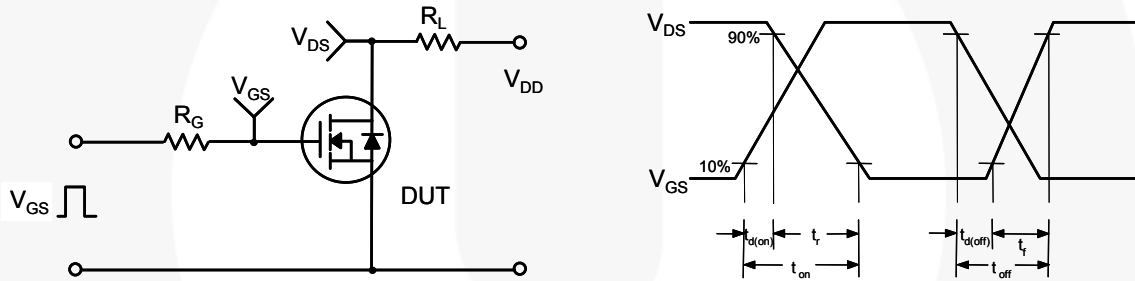


Figure 13. Resistive Switching Test Circuit & Waveforms

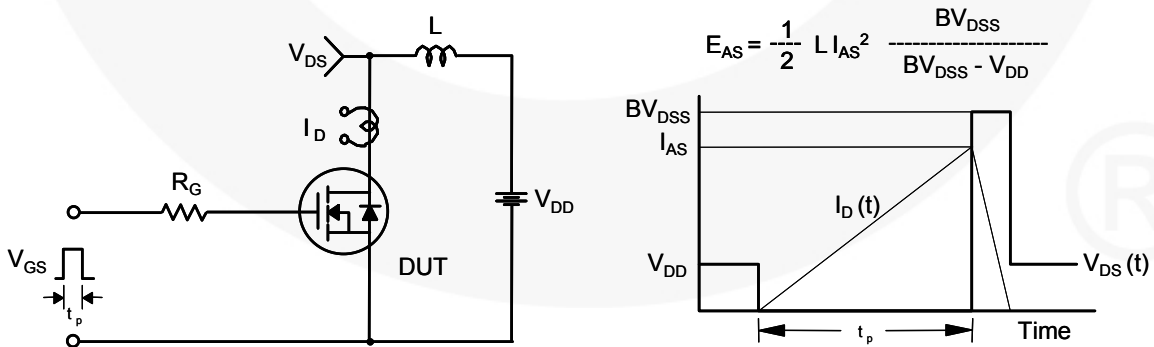


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

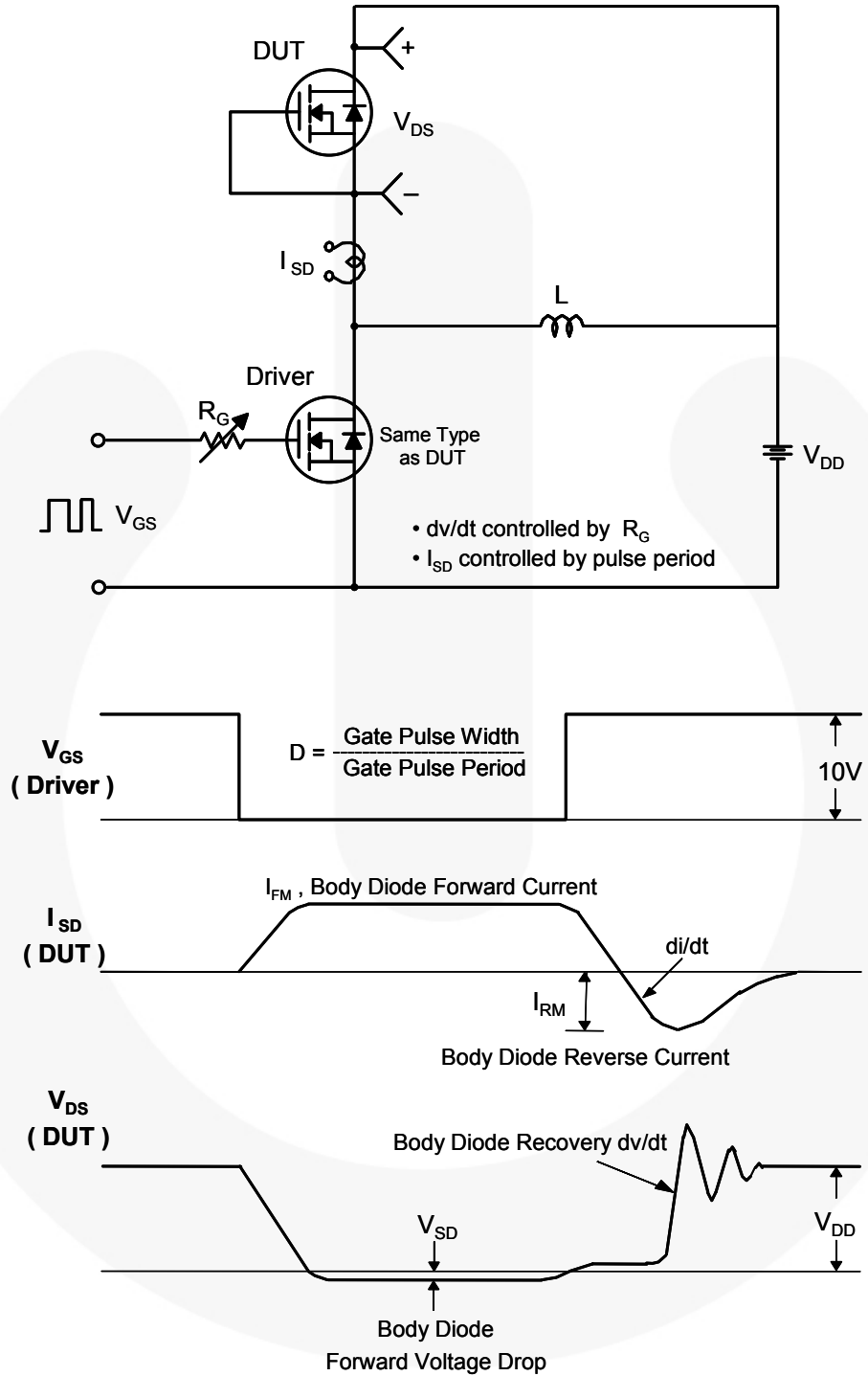
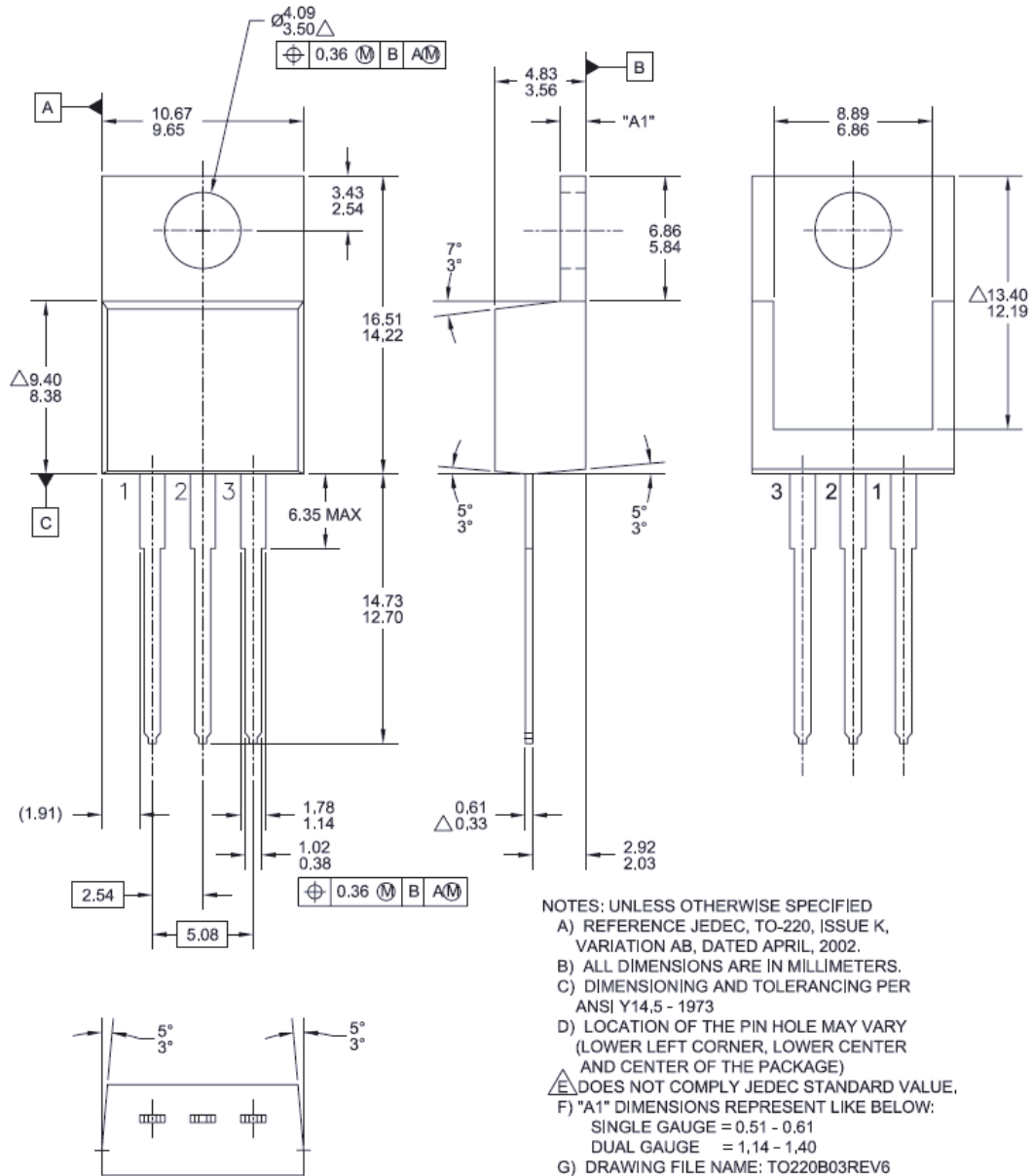


Figure 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

### Mechanical Dimensions



**Figure 16. TO-220, Molded, 3-Lead, Jedec Variation AB**

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| Fairchild Semiconductor® | SPM®                    | SuperSOT™-3                                     | UniFET™          |
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| FACT®                    | SuperFET®               | SuperSOT™-8                                     | VisualMax™       |
| FAST®                    | SupreMOS®               | SyncFET™  | VoltagePlus™     |
| FastvCore™               | SyncFET™                |   | XS™              |
| FETBench™                |                         |   |                  |
| FPS™                     |                         |   |                  |

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